Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ***** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2015-04-01
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	**Representative Title**	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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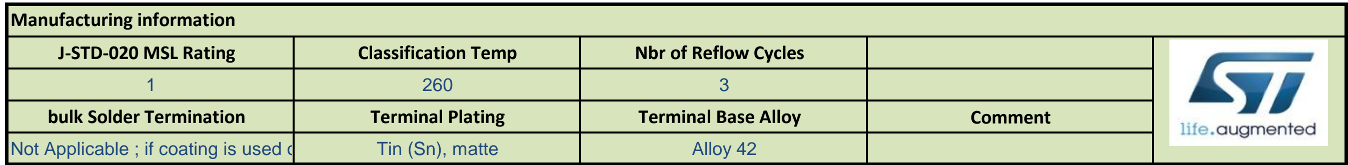
Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HJW9*AAY02VC	A	Z55A	2015-04-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	6.576	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
DSO	2 - 1.26 - 0.93	3	gull wing	
Comment	Package: SOT 323 - 3 LEADS; MDF valid for ESDCAN02-1BWY; ESDLIN03-1BWY			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HJW9*AAY02VC						
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**	
Silicon Die	Other Inorganic Material	0.331	mg	supplier	die	Silicon (Si)	7440-21-3		0.309	mg	933535	46989	
Silicon Die			mg	supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	3021	152	
Silicon Die			mg	supplier	metallization	Copper (Cu)	7440-50-8		0.016	mg	48338	2433	
Silicon Die			mg	supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.001	mg	3021	152	
Silicon Die			mg	supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.004	mg	12085	608	
Leadframe	Other Ferrous alloys, non-stainless ste	1.83	mg	Supplier	Alloy	Iron (Fe)	7439-89-6		1.056	mg	577049	160584	
Leadframe			mg	Supplier	Alloy	Nickel (Ni)	7440-02-0		0.753	mg	411475	114507	
Leadframe			mg	Supplier	Alloy	Manganese (Mn)	7439-96-5		0.01	mg	5464	1521	
Leadframe			mg	Supplier	Alloy	Cobalt (Co)	7440-48-4		0.009	mg	4918	1369	
Leadframe			mg	Supplier	Alloy	Silicon (Si)	7440-21-3		0.002	mg	1093	304	
Die Attach	Other Organic Material	0.081	mg	Supplier	Glue	Treated silica	60676-86-0		0.002	mg	24691	304	
Die Attach			mg	Supplier	Glue	Glycol ethers	Proprietary		0.008	mg	98765	1217	
Die Attach			mg	Supplier	Glue	Metal Oxide	1344-28-1		0.01	mg	123457	1521	
Die Attach			mg	Supplier	Glue	Curing agent & hardener	Proprietary		0.002	mg	24691	304	
Die Attach			mg	Supplier	Glue	Epoxy resin	Proprietary		0.01	mg	123457	1521	
Die Attach			mg	Supplier	Glue	Epoxyde Bisphenol A Resin	25068-38-6		0.012	mg	148148	1825	
Die Attach			mg	Supplier	Glue	Diaminodiphenylsulfone	80-08-0		0.003	mg	37037	456	
Die Attach			mg	Supplier	Glue	Ethoxyethoxy-ethyl Acetate	112-15-2		0.023	mg	283951	3498	
Die Attach			mg	Supplier	Glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.011	mg	135802	1673	
Bonding Wire	Other Inorganic Material	0.056	mg	Supplier	Bonding Wire	Copper (Cu)	7440-50-8		0.055	mg	982143	8364	
Bonding Wire			mg	Supplier	Bonding Wire	Palladium (Pd)	7440-05-3		0.001	mg	17857	152	
Encapsulation	Other Organic Material	4.029	mg	Supplier	Molding Compound	phenolic resin	26834-02-6		0.096	mg	23827	14599	
Encapsulation			mg	Supplier	Molding Compound	epoxy resin	29690-82-2		0.096	mg	23827	14599	
Encapsulation			mg	Supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		0.143	mg	35493	21746	
Encapsulation			mg	Supplier	Molding Compound	Silica	60676-86-0		3.678	mg	912882	559307	
Encapsulation			mg	Supplier	Molding Compound	Carbon Black	1333-86-4		0.007	mg	1737	1064	
Encapsulation			mg	Supplier	Molding Compound	Tetrakis(2,6-dimethylphenyl) 1,3-phenylene bis	139189-30-3		0.009	mg	2234	1369	
connections coating	Solder	0.249	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.249	mg	1000000	37865	